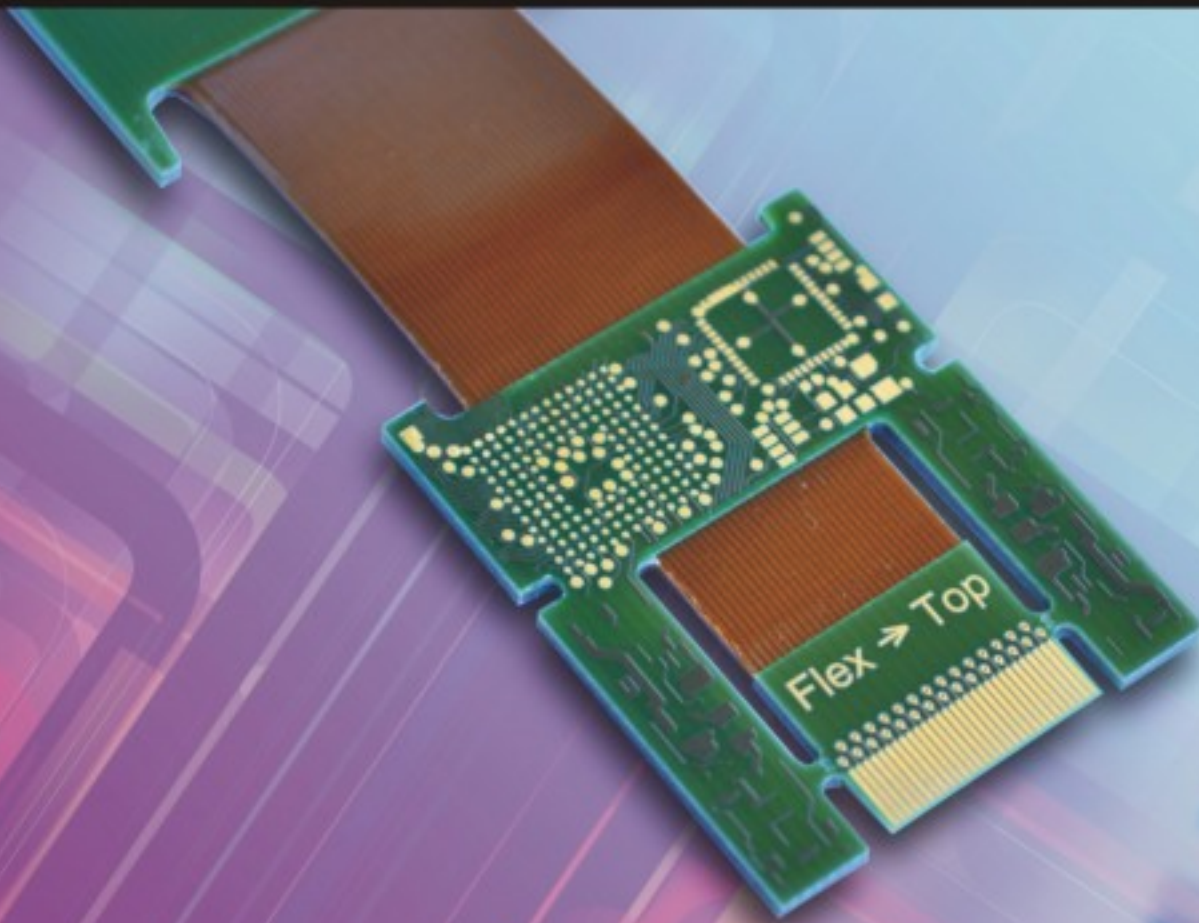


# SENSORS & TRANSDUCERS

ISSN 1726-5479

vol. 152  
**5/13**



**Sensor Buses and Interfaces**

International Frequency Sensor Association Publishing



# Sensors & Transducers

**International Official Journal of the International  
Frequency Sensor Association (IFSA) Devoted to  
Research and Development of Sensors and Transducers**

Volume 152, Issue 5, May 2013

---

**Editor-in-Chief**  
Sergey Y. YURISH



IFSA Publishing: Barcelona • Toronto

Copyright © 2013 IFSA Publishing. All rights reserved.

This journal and the individual contributions in it are protected under copyright by IFSA Publishing, and the following terms and conditions apply to their use:

*Photocopying:* Single photocopies of single articles may be made for personal use as allowed by national copyright laws. Permission of the Publisher and payment of a fee is required for all other photocopying, including multiple or systematic copyright, copyright for advertising or promotional purposes, resale, and all forms of document delivery.

*Derivative Works:* Subscribers may reproduce tables of contents or prepare list of articles including abstract for internal circulation within their institutions. Permission of the Publisher is required for resale or distribution outside the institution.

Permission of the Publisher is required for all other derivative works, including compilations and translations.

Authors' copies of Sensors & Transducers journal and articles published in it are for personal use only.

Address permissions requests to: IFSA Publisher by e-mail: [editor@sensorsportal.com](mailto:editor@sensorsportal.com)

Notice: No responsibility is assumed by the Publisher for any injury and/or damage to persons or property as a matter of products liability, negligence or otherwise, or from any use or operation of any methods, products, instructions or ideas contained in the material herein.

Printed in the USA.



# Sensors & Transducers

Volume 152, Issue 5,  
May 2013

www.sensorsportal.com

ISSN 2306-8515  
e-ISSN 1726-5479

**Editors-in-Chief:** professor Sergey Y. Yurish,  
Tel.: +34 696067716, e-mail: editor@sensorsportal.com

## Editors for Western Europe

Meijer, Gerard C.M., Delft Univ. of Technology, The Netherlands  
Ferrari, Vittorio, Università di Brescia, Italy

## Editor for Eastern Europe

Sachenko, Anatoly, Ternopil National Economic University, Ukraine

## Editors for North America

Katz, Evgeny, Clarkson University, USA  
Datskos, Panos G., Oak Ridge National Laboratory, USA  
Fabien, J. Josse, Marquette University, USA

## Editor South America

Costa-Felix, Rodrigo, Inmetro, Brazil

## Editors for Asia

Ohyama, Shinji, Tokyo Institute of Technology, Japan  
Zhengbing, Hu, Huazhong Univ. of Science and Technol., China

## Editor for Asia-Pacific

Mukhopadhyay, Subhas, Massey University, New Zealand

## Editor for Africa

Maki K.Habib, American University in Cairo, Egypt

## Editorial Board

**Abdul Rahim, Ruzairi**, Universiti Teknologi, Malaysia  
**Abramchuk, George**, Measur. Tech. & Advanced Applications, Canada  
**Ascoli, Giorgio**, George Mason University, USA  
**Atalay, Selcuk**, Inonu University, Turkey  
**Atghiaee, Ahmad**, University of Tehran, Iran  
**Augutis, Vygtantas**, Kaunas University of Technology, Lithuania  
**Ayesh, Aladdin**, De Montfort University, UK  
**Baliga, Shankar, B.**, General Monitors, USA  
**Basu, Sukumar**, Jadavpur University, India  
**Bousbia-Salah, Mounir**, University of Annaba, Algeria  
**Bouvet, Marcel**, University of Burgundy, France  
**Campanella, Luigi**, University La Sapienza, Italy  
**Carvalho, Vitor**, Minho University, Portugal  
**Changhai, Ru**, Harbin Engineering University, China  
**Chen, Wei**, Hefei University of Technology, China  
**Cheng-Ta, Chiang**, National Chia-Yi University, Taiwan  
**Chung, Wen-Yaw**, Chung Yuan Christian University, Taiwan  
**Cortes, Camilo A.**, Universidad Nacional de Colombia, Colombia  
**D'Amico, Arnaldo**, Università di Tor Vergata, Italy  
**De Stefano, Luca**, Institute for Microelectronics and Microsystem, Italy  
**Ding, Jianning**, Changzhou University, China  
**Djordjevich, Alexander**, City University of Hong Kong, Hong Kong  
**Donato, Nicola**, University of Messina, Italy  
**Dong, Feng**, Tianjin University, China  
**Erkmen, Aydan M.**, Middle East Technical University, Turkey  
**Gaura, Elena**, Coventry University, UK  
**Gole, James**, Georgia Institute of Technology, USA  
**Gong, Hao**, National Institute of Singapore, Singapore  
**Gonzalez de la Rosa, Juan Jose**, University of Cadiz, Spain  
**Guillet, Bruno**, University of Caen, France  
**Hadjiloucas, Sillas**, The University of Reading, UK  
**Hao, Shiyong**, Michigan State University, USA  
**Hui, David**, University of New Orleans, USA  
**Jaffrezic-Renault, Nicole**, Claude Bernard University Lyon 1, France  
**Jamil, Mohammad**, Qatar University, Qatar  
**Kaniusas, Eugenijus**, Vienna University of Technology, Austria  
**Kim, Min Young**, Kyungpook National University, Korea  
**Kumar, Arun**, University of Delaware, USA  
**Lay-Ekuakille, Aime**, University of Lecce, Italy  
**Li, Si**, GE Global Research Center, USA  
**Lin, Paul**, Cleveland State University, USA  
**Liu, Aihua**, Chinese Academy of Sciences, China

**Mahadi, Muhammad**, University Tun Hussein Onn Malaysia, Malaysia  
**Mansor, Muhammad Naufal**, University Malaysia Perlis, Malaysia  
**Marquez, Alfredo**, Centro de Investigacion en Materiales Avanzados, Mexico  
**Mishra, Vivekanand**, National Institute of Technology, India  
**Moghavvemi, Mahmoud**, University of Malaya, Malaysia  
**Morello, Rosario**, University "Mediterranea" of Reggio Calabria, Italy  
**Mulla, Intiaz Sirajuddin**, National Chemical Laboratory, Pune, India  
**Nabok, Aleksey**, Sheffield Hallam University, UK  
**Neshkova, Milka**, Bulgarian Academy of Sciences, Bulgaria  
**Passaro, Vittorio M. N.**, Politecnico di Bari, Italy  
**Penza, Michele**, ENEA, Italy  
**Pereira, Jose Miguel**, Instituto Politecnico de Setebal, Portugal  
**Pogacnik, Lea**, University of Ljubljana, Slovenia  
**Pullini, Daniele**, Centro Ricerche FIAT, Italy  
**Reig, Candid**, University of Valencia, Spain  
**Restivo, Maria Teresa**, University of Porto, Portugal  
**Rodríguez Martínez, Angel**, Universidad Politécnica de Cataluña, Spain  
**Singhal, Subodh Kumar**, National Physical Laboratory, India  
**Sadeghian Marnani, Hamed**, TU Delft, The Netherlands  
**Sapozhnikova, Ksenia**, D. I. Mendeleev Institute for Metrology, Russia  
**Singhal, Subodh Kumar**, National Physical Laboratory, India  
**Shah, Kriyang**, La Trobe University, Australia  
**Shi, Wendian**, California Institute of Technology, USA  
**Shmaliy, Yuriy**, Guanajuato University, Mexico  
**Song, Xu**, An Yang Normal University, China  
**Srivastava, Arvind K.**, LightField, Corp, USA  
**Stefanescu, Dan Mihai**, Romanian Measurement Society, Romania  
**Sumriddetchkajorn, Sarun**, Nat. Electr. & Comp. Tech. Center, Thailand  
**Sun, Zhiqiang**, Central South University, China  
**Sysoev, Victor**, Saratov State Technical University, Russia  
**Thirunavukkarasu, I.**, Manipal University Karnataka, India  
**Thomas, Sadiq**, Heriot Watt University, Edinburgh, UK  
**Tianxing, Chu**, Research Center for Surveying & Mapping, Beijing, China  
**Vazquez, Carmen**, Universidad Carlos III Madrid, Spain  
**Wang, Jiangping**, Xian Shiyou University, China  
**Xue, Ning**, Agiltron, Inc., USA  
**Yang, Dongfang**, National Research Council, Canada  
**Yang, Shuang-Hua**, Loughborough University, UK  
**Yaping Dan**, Harvard University, USA  
**Zakaria, Zulkarnay**, University Malaysia Perlis, Malaysia  
**Zhang, Weiping**, Shanghai Jiao Tong University, China  
**Zhang, Wenming**, Shanghai Jiao Tong University, China

# Contents

Volume 152  
Issue 5  
May 2013

www.sensorsportal.com

ISSN: 2306-8515  
e-ISSN 1726-5479

## Research Articles

- Research on the Structure and Signal Transmission of Rotary Piezoelectric Dynamometer**  
*Zhenyuan Jia, Yongyan Shang, Zongjin Ren, Yifei Gao and Shengnan Gao* ..... 1
- Piezoelectric Sensor of Control Surface Hinge Moment**  
*Zongjin Ren, Shengnan Gao, Zhenyuan Jia, Yongyan Shang and Yifei Gao* ..... 11
- Research Algorithm on Building Intelligent Transportation System based on RFID Technology**  
*Chuanqi Chen* ..... 18
- Using Displacement Sensor to Determinate the Fracture Toughness of PMMA Bone Cement**  
*Yongzhi Xu, Youzhi Wang* ..... 27
- Study on the Applications of Fiber Bragg Grating and Wireless Network Technologies in Telemetry System of Atmospheric Precipitation**  
*Han Bing, Tan Dongjie, Li Liangliang, Liu Jianping* ..... 33
- An Energy-Efficient Adaptive Clustering Protocol for Wireless Sensor Network**  
*Lü Tao, Zhu Qing-Xin, Zhu Yu-Yu* ..... 41
- A Case Study of Event Detection Performance Measure in WSNs Using Gini Index**  
*Luhutyit Peter Damuut, Dongbing Gu* ..... 51
- Fault Diagnosis of Tool Wear Based on Weak Feature Extraction and GA-B-spline Network**  
*Weiqing Cao, Pan Fu, Genhou Xu* ..... 60
- The Research Abort Concept Restructuring of the Sensor Semantic Networks**  
*Guanwei* ..... 68
- Coordinating Reasoning Method for Semantic Sensor Networks**  
*Shi Yun Ping* ..... 76
- A Novel Intelligent Transportation Control Supported by Wireless Sensor Network**  
*Zhe Qian, Jianqi Liu* ..... 84
- Research on the Special Railway Intelligence Transportation Hierarchy and System Integration Methodology**  
*Meng-Jie Wang, Xi-Fu Wang, Wen-Ying Zhang, Xue Feng* ..... 89
- Application of a Heterogeneous Wireless Framework for Radiation Monitoring in Nuclear Power Plant**  
*Gu Danying* ..... 98

<b>Acoustic Emission Signal Analysis of Aluminum Alloy Fatigue Crack</b> <i>Wenxue Qian, Xiaowei Yin, Liyang Xie</i> .....	105
<b>A New Ultra-lightweight Authentication Protocol for Low Cost RFID Tags</b> <i>Xin Wang, Qingxuan Jia, Xin Gao, Peng Chen, Bing Zhao</i> .....	110
<b>AGC Design in Frequency Modulation System for Voice Communication via Underwater Acoustic Channel</b> <i>Cheng En, Chen Sheng-Li, Li Ye, Ke Fu-Yuan, Yuan Fei</i> .....	116
<b>Joint Source-Channel Coding for Underwater Image Transmission</b> <i>Chen Hua-Bin, Chen Wei-Ling, Li Ye, Cheng En, Yuan Fei</i> .....	122
<b>Study on the Applications of Cross-Layer Information Fusion in Target Recognition</b> <i>Xing Liu, Shoushan Jiang</i> .....	129
<b>A Simple Tree Detector Using Laser and Camera Fusion</b> <i>D. Wang, J. H. Liu, J. L. Wang, T. Li</i> .....	137
<b>Simulation and Analysis of T-Junction Microchannel</b> <i>Kainat Nabi, Rida Rafi, Muhammad Waseem Ashraf, Shahzadi Tayyaba, Zahoor Ahmad, Muhammad Imran, Faran Baig and Nitin Afzulpurkar</i> .....	146
<b>Mass Flow Measurement of Fluids by a Helically Coiled Tube</b> <i>Tian Zhou, Zhiqiang Sun, Zhenying Dong, Saiwei Li, Jiemin Zhou</i> .....	152
<b>Comparative Creep Evaluation between the Use of ISO 376 and OIML R60 for Silicon Load Cell Characterization</b> <i>Ebtisam H. Hasan, Rolf Kumme, Günther Haucke and Sascha Mäuselein</i> .....	158
<b>Development of Noise Measurements. Part 3. Passive Method of Electronic Elements Quality Characterization</b> <i>Yuriy Bobalo, Zenoviy Kolodiy, Bohdan Stadnyk, Svyatoslav Yatsyshyn</i> .....	164
<b>Application of Mixed Programming in the Simulation of Lorenz Chaotic System's Dynamics Characteristics Based on Labview and Matlab</b> <i>Peng Zhou, Gang Xu, Liang Chen</i> .....	169
<b>A Nanostructure with Dual-Band Plasmonic Resonance and Its Sensing Application</b> <i>Zongheng Yuan, Jing Huan , Xiaonan Li and Dasen Ren</i> .....	174
<b>A Glucose Sensor Based on Glucose Oxidase Immobilized by Electrospinning Nanofibrous Polymer Membranes Modified with Carbon Nanotubes</b> <i>You Wang, Hui Xu, Zhengang Wang, Ruifen Hu, Zhiyuan Luo, Zhikang Xu, Guang Li</i> .....	180
<b>The Platform Architecture and Key Technology of Cloud Service that Support Wisdom City Management</b> <i>Liang Xiao</i> .....	186

Authors are encouraged to submit article in MS Word (doc) and Acrobat (pdf) formats by e-mail: editor@sensorsportal.com  
Please visit journal's webpage with preparation instructions: <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm>

## Digital Sensors and Sensor Systems: Practical Design

Sergey Y. Yurish



Formats: printable pdf (Acrobat) and print (hardcover), 419 pages

ISBN: 978-84-616-0652-8,  
e-ISBN: 978-84-615-6957-1

The goal of this book is to help the practitioners achieve the best metrological and technical performances of digital sensors and sensor systems at low cost, and significantly to reduce time-to-market. It should be also useful for students, lectures and professors to provide a solid background of the novel concepts and design approach.

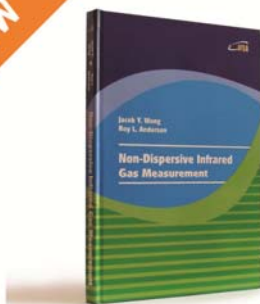
### Book features include:

- Each of chapter can be used independently and contains its own detailed list of references
- Easy-to-repeat experiments
- Practical orientation
- Dozens examples of various complete sensors and sensor systems for physical and chemical, electrical and non-electrical values
- Detailed description of technology driven and coming alternative to the ADC a frequency (time)-to-digital conversion

*Digital Sensors and Sensor Systems: Practical Design* will greatly benefit undergraduate and at PhD students, engineers, scientists and researchers in both industry and academia. It is especially suited as a reference guide for practitioners, working for Original Equipment Manufacturers (OEM) electronics market (electronics/hardware), sensor industry, and using commercial-off-the-shelf components

[http://sensorsportal.com/HTML/BOOKSTORE/Digital\\_Sensors.htm](http://sensorsportal.com/HTML/BOOKSTORE/Digital_Sensors.htm)

**NEW BOOK**



Formats: printable pdf (Acrobat) and print (hardcover), 120 pages

ISBN: 978-84-615-9732-1,  
e-ISBN: 978-84-615-9512-9

Jacob Y. Wong, Roy L. Anderson

## Non-Dispersive Infrared Gas Measurement

Written by experts in the field, the *Non-Dispersive Infrared Gas Measurement* begins with a brief survey of various gas measurement techniques and continues with fundamental aspects and cutting-edge progress in NDIR gas sensors in their historical development.

- It addresses various fields, including:
  - Interactive and non-interactive gas sensors
  - Non-dispersive infrared gas sensors' components
  - Single- and Double beam designs
  - Historical background and today's of NDIR gas measurements

Providing sufficient background information and details, the book *Non-Dispersive Infrared Gas Measurement* is an excellent resource for advanced level undergraduate and graduate students as well as researchers, instrumentation engineers, applied physicists, chemists, material scientists in gas, chemical, biological, and medical sensors to have a comprehensive understanding of the development of non-dispersive infrared gas sensors and the trends for the future investigation.

[http://sensorsportal.com/HTML/BOOKSTORE/NDIR\\_Gas\\_Measurement.htm](http://sensorsportal.com/HTML/BOOKSTORE/NDIR_Gas_Measurement.htm)

## Acoustic Emission Signal Analysis of Aluminum Alloy Fatigue Crack

<sup>1</sup>Wenxue Qian, <sup>2</sup>Xiaowei Yin, <sup>1</sup>Liyang Xie

<sup>1</sup>School of Mechanical Engineering & Automation, Northeastern University, Shenyang 110819, China

<sup>2</sup>Department of Mechanical Engineering, Shenyang Institute of Engineering, Shenyang, 110136, China  
E-mail: Qwx99@163.com

Received: 26 April 2013 /Accepted: 15 May 2013 /Published: 27 May 2013

---

**Abstract:** Fatigue fracture is the most common failure mode of engineering equipment. It is difficult to monitor the fatigue crack because the fatigue crack is very small. The sizes of fatigue cracks are about several micrometers to several decade millimeters. Acoustic emission (AE) of material is a common phenomenon; In fact, it has relation with the material states. In this paper, the acoustic emission test method about crack is used and the characteristics of different phases of aluminum alloy cracks are analyzed. Practical test shows the AE method could detect the cracks that common method could not detect them. To predict the length of crack precisely is important. AE can predict the size of crack quite well. The result is of practical engineering significance. *Copyright © 2013 IFSA.*

**Keywords:** Acoustic emission, Fatigue damage, Signal analysis.

---

### 1. Introduction

Engineering equipments often fail while running or not running. That usually causes casualties and property losses. For mechanical structures, fracture is the most common failure mode. However, it is difficult to monitor the cracks while the equipment is running. Acoustic emission (AE) is a common phenomenon. Usually it is the stress wave produced by the sudden internal stress redistribution of the material caused by the changes in the internal structure. Possible causes of the internal-structure changes are crack initiation and growth, crack opening and closure, twinning, dislocation movement, and phase transformation in monolithic materials. Most of the sources of AEs are damage-related; thus the detection and monitoring of these emissions are very useful to predict material failure. Besides the

applications of AE in research endeavors, AE has been widely used in industries, including for the detection of faults or leakage in pressure vessels, piping systems, and tanks. AE is also a good method to monitor the welding and corrosion progress [1-7].

Acoustic emissions can be created in a controlled environment, and they can also occur naturally. Therefore, as a means of quality control, the origin of AE is hard to pinpoint. As early as 6,500 BC, potters were known to listen for audible sounds during the cooling of their ceramics, signifying structural failure. After 1900's, many scientists' works advanced the research. Joseph Kaiser did a lot of work on AE, and his research is generally recognized as the beginning of modern day acoustic emission testing.

There are two differences between the AE technique and other nondestructive evaluation (NDE) methods; the first difference is that AE detects the

activities inside the materials, while other NDE methods attempt to examine the internal structures of the materials. Furthermore, AE only needs the input of one or more relatively small sensors on the surface of the structure or specimen being examined so that the structure or specimen can be subjected to the in-service or laboratory operation while the AE system continuously monitors the progressive damage. Other NDE methods, such as ultrasound and x-ray, have to access the whole structure or specimen, and therefore, the structure or specimen often needs to be disassembled and taken to the laboratory to be examined, the second difference is that AE deals with dynamic processes, or changes, in a material. This is particularly meaningful because only active features are highlighted. The ability to discern between developing and stagnant defects is significant. However, it is possible for flaws to go undetected altogether if the loading is not high enough to cause an acoustic event. Furthermore, AE testing usually provides an immediate indication relating to the strength or risk of failure of a component. Other advantages of AET include fast and complete volumetric inspection using multiple sensors, permanent sensor mounting for process control, and no need to disassemble and clean a specimen [8].

The disadvantage of AE is that commercial AE systems can only estimate qualitatively how much damage is in the material and approximately how long the components will last. So, other NDE methods are still needed to do more thorough examinations and provide quantitative results. Moreover, service environments are generally very noisy, and the AE signals are usually very weak. Thus, signal discrimination and noise reduction are very important [9-13].

## 2. Specimens and Sensors Layout

### A. AE test of tensile specimen

Lots of research results showed that different material has different properties and the same material has the same characteristics. To gain the AE properties of a material, it is necessary to obtain the characteristics of static tensile test. Hereinafter a tensile test of aluminum alloy will be done to get its basic characteristics. The drawing of the specimen is shown in Fig. 1.

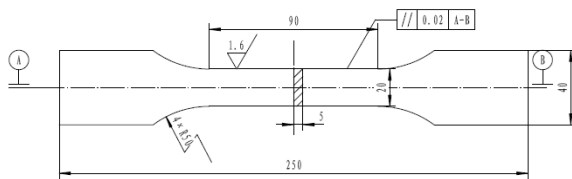


Fig. 1. Tensile specimen.

The instrument which is used in the test is PCI-2 Acoustic emissions instrument; it is a product of PAC Company of USA. The tensile testing machine which is used is WDW-100 tensile testing machine, it is a computer controlled machine, the largest load is 100 KN and the tensile velocity is 1mm/min. Fig. 1 and Fig. 2 are the specimen drawings and sensors layout.

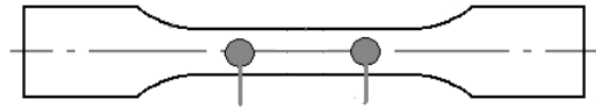


Fig. 2. Sensors location on tensile specimen

### B. AE test of fatigue crack

Fatigue failure is a quite common failure mode of Mechanical components. So it is significant to study the behavior of AE of fatigue crack. In this research, the notched specimen is designed as Fig. 3 and the sensors layout is shown in Fig. 4. The sizes of notched specimen are the same as tensile specimen except the notch. The model of fatigue apparatus is PLS-100 electro-hydraulic servo fatigue testing machine. The maximum load is  $F_{max} = 100$  KN and the maximum stroke is 50 mm. Fatigue test parameters is as follows: stress ratio:  $r = 0.1$ , frequency:  $f = 10$  Hz, mean load:  $F_m = 8.8$  KN, load amplitude:  $F_a = 7.2$  KN, the cross section of notched part:  $A = 85$  mm<sup>2</sup>, the maximum nominal stress of the cross section of notched part:  $S_{max} = 82.35$  MPa. Based on above data the stress concentration factor of notched specimen is 2.0. When testing, after a certain period, stop the machine and a replica method was used to get the crack shape and size. Then the crack can be measured under microscope and the length of crack was write down, at the same time, the cyclic number was enregistered. When the crack was large enough, it could be observed through reading microscope. To do the experiment, the parameters in Table 1 are used.

Table 1. Parameters of AE test.

Parameters	Values
Frequency (kHz)	100~1000
Preamplifier plus (dB)	40
Threshold (dB)	40
PDT (μs)	300
HDT (μs)	600
HLT (μs)	1000
Sampling frequency (MHz)	5
Highpass filtering (MHz)	0.1
Lowpass filtering (MHz)	1

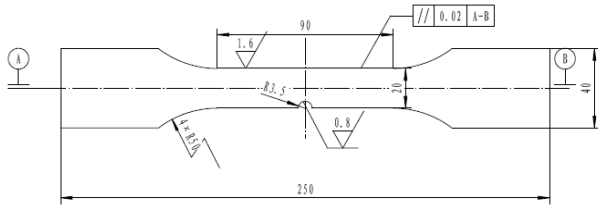


Fig. 3. Notch specimen.

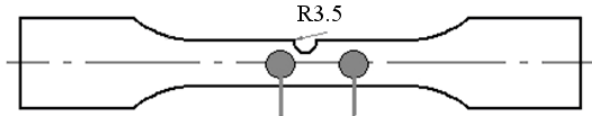


Fig. 4. Sensors location on notch specimen.

### 3. Results and Discussion

The stress - strain curve of tensile test of aluminum alloy and the counts number every 0.2 s is shown in Fig. 5. The accumulation of counts of AE along with time is shown in Fig. 6. Through Fig. 5 and Fig. 6 it is seen that the curve of accumulation of counts and the stress-strain curve is alike.

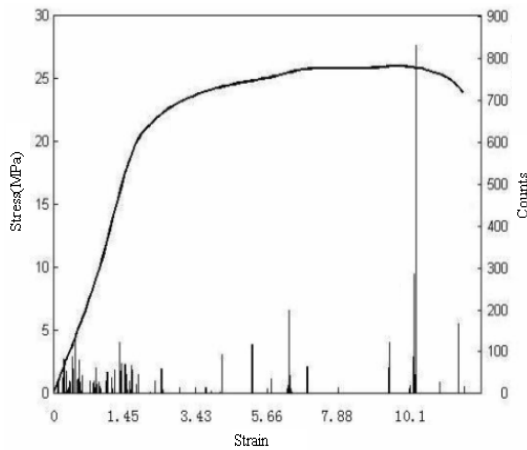


Fig. 5. Stress – strain curve and AE counts.

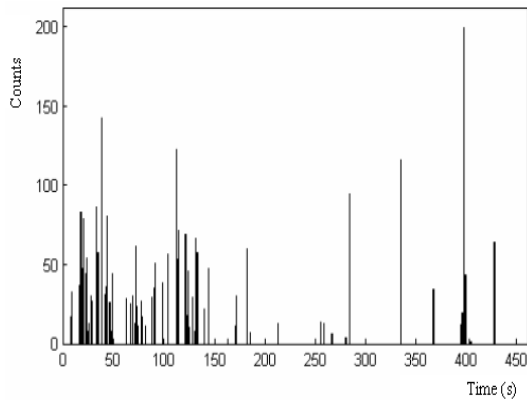


Fig. 6. Time history of counts.

In Fig. 5 and Fig. 6, there are two periods that the AE counts raise quickly; the reason of AE counts increase quickly is the fault of the material and plastic deform, and the reason of AE counts increase quickly is the crack propagation. Fig. 7 is the accumulative curve of counts.

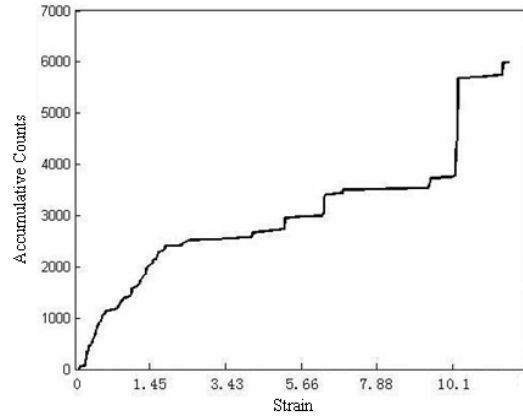


Fig. 7. Accumulative curve of counts.

The fatigue test results of specimens were analyzed. The sensor of the second channel collected the hits, counts and energy signals. Fig. 8 - Fig. 10 are the statistical figures about hits, counts and energy in one second. The Waveform and frequency spectrogram of a single hit are shown as Fig. 11 and Fig. 12.

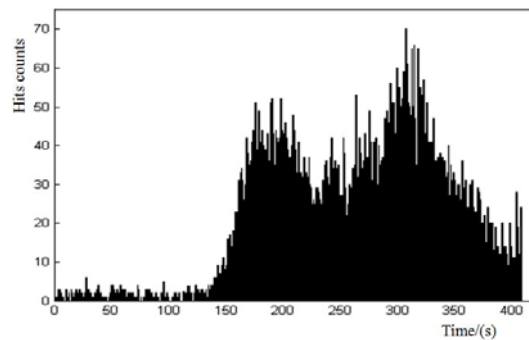


Fig. 8. Statistical chart of hits.

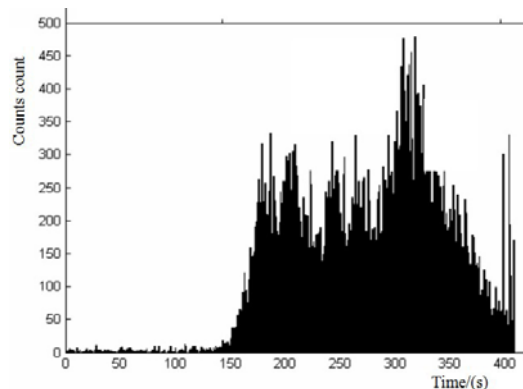


Fig. 9. Statistical chart of counts.

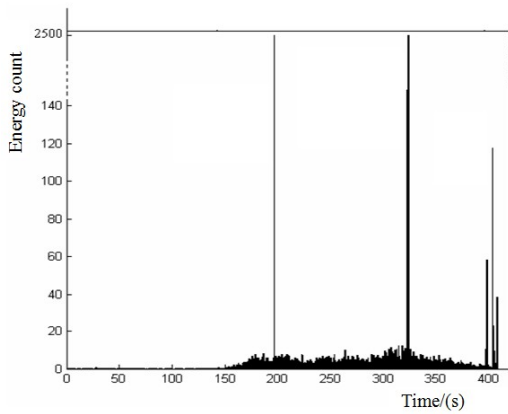


Fig. 10. Statistical chart of energy.

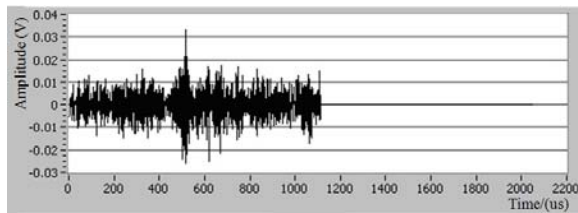


Fig. 11. Waveform of hits.

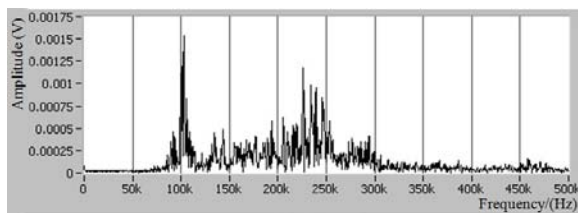


Fig. 12. Frequency analysis.

Through replica method and statistic analysis of acoustic emission signal, it can be seen that the acoustic emission signals of fatigue crack are much more complex than those of tensile test. From test it can be seen the characteristic of are different at different phase of fatigue crack including fatigue crack initiation, fatigue crack propagation and fatigue crack unstable extension. While crack initiation the acoustic emission signals are very weak. When several small crack coalesce, the acoustic emission signals became stronger and with high energy as shown in Fig. 9. In addition, when during the phase of crack quick propagation and fracture, there are a lot of acoustic emission signals sent out. From frequency analysis as shown in Fig. 12, it can be seen that the frequencies of acoustic emission signals are mainly concentrate between 100 kHz – 300 kHz. Usually liquid flow noise of the hydraulic system and mechanical impact noise frequency are less than 100 kHz. However, for the noise of mechanical friction, its frequencies are close to the frequencies of acoustic emission signals of crack. On this occasion, it is difficult to exclude the noise signals by

Frequency domain analysis. Through the test results, it can be seen that the energy of acoustic emission signals is larger than the energy of noise signals. In this condition, we can improve the threshold to filter out the noise.

#### 4. Conclusions

AE is a powerful NDT method; in this paper the behaviour of AE of a certain aluminum alloy material is studied. The advantage of AE to detect cracks is that the locations of cracks have little effect on the results. In this paper the properties of AE of fatigue crack are studied. The results shows that the frequency of AE of fatigue crack between 100 kHz – 300 kHz and at different period of crack propagation the characteristics of AE are different. At the period of crack initiation and quick propagation, there are lots of AE signals and the parameters such as counts, hits and energy etc. all changed relatively. When using the auxiliary method such as replica method and microscope method as compare, AE can predict the size of crack quite well; it is significant to engineering practice.

#### Acknowledgements

This work was partially supported by the National Natural Science Foundation of China (Grant No. 51005044, 51175072, 51275221), the Program for Liaoning Excellent Talents in University, and the Fundamental Research Funds for the Central Universities (Grant No. N100403001, N120403014).

#### References

- [1]. Adamo, M., Bonavolonta, C., Valentino, M. Investigation of Artificial Cracks by Scanning SQUID Magnetic Microscope, *Sensor Letters*, 3, 7, 2009, pp. 397-399.
- [2]. C. Ennaceur, A. Laksimi, C. Herve, M. Cherfaoui. Monitoring Crack Growth in Pressure Vessel Steels by the Acoustic Emission Technique and the Method of Potential Difference, *International Journal of Pressure Vessels and Piping*, 83, 2006, pp. 197-204.
- [3]. Qian Wenxue, Yin Xiaowei, Xie Liyang. System Reliability Allocation Based on Bayesian Network, *Applied Mathematics & Information Sciences*, 6, 3, 2012, pp. 681-687.
- [4]. Xie Liyang, Zhou Jinyu, Wang Xuemin. Data mapping and the prediction of common cause failure probability, *IEEE Transactions on Reliability*, 54, 2005, pp. 291 - 296.
- [5]. Qian Wenxue, Xie Liyang, Yin Xiaowei. Reliability modeling and assessment of load dependent multiple weak site parts, *Journal of Mechanical Engineering*, 46, 2010, pp. 182 - 187.
- [6]. Alberto Pasquini, Simone Pozzi, Gerard McAuley. Eliciting Information for Safety Assessment, *Safety Science*, 46, 10, 2008, pp. 1469-1482.
- [7]. Mazrou H. and Hamadouche M. Application of artificial neural network for safety core parameters

- prediction in LWRRS, *Progress in Nuclear Energy*, 44, 3, 2004, pp. 263-215.
- [8]. S. T. Ung, V. Williams, S. Bonsall, J. Wang. Test case based risk predictions using artificial neural network, *Journal of Safety Research*, 37, 2006, pp. 245 – 260.
- [9]. Mazrou H., Hamadouche M. Application of Artificial Neural Network for Safety Core Parameters Prediction In LWRRS, *Progress in Nuclear Energy*, 44, 3, 2004, pp. 263-215.
- [10]. S. T. Ung, V. Williams, S. Bonsall, J. Wang. Test Case Based Risk Predictions Using Artificial Neural Network, *Journal of Safety Research*, 37, 2006, pp. 245 – 260.
- [11]. Jang, C. S., Kim, C. H. Application of a Neural Network for Prediction of Two-Dimensional Power Distribution in Pwrs, *Trans. Am. Nucl. Soc.*, 76, 2006, pp. 156 – 166.
- [12]. Recep Kazan, Mehmet Firat, Aysun Egrisogut Tiryaki. Prediction of Springback in Wipe-Bending Process of Sheet Metal Using Neural Network, *Materials & Design*, 30, 2, 2009, pp. 418-423.
- [13]. G. Partheepan, D. K. Sehgal, R. K. Pandey, Fracture Toughness Evaluation Using Miniature Specimen Test and Neural Network, *Computational Materials Science*, 44, 2, 2008, pp. 523-530.

2013 Copyright ©, International Frequency Sensor Association (IFSA). All rights reserved.  
(<http://www.sensorsportal.com>)



**Universal Frequency-to-Digital Converter  
(UFDC-1 and UFDC-1M-16)  
in MLF (5 x 5 x 1 mm) package**

**SMALL WORLD -  
BIG FEATURES**

SWP, Inc., Toronto, Ontario, Canada,  
Tel. + 34 696067716, fax: +34 93 4011989, e-mail: [sales@sensorsportal.com](mailto:sales@sensorsportal.com)  
[http://www.sensorsportal.com/HTML/E-SHOP/PRODUCTS\\_4/UFDC\\_1.htm](http://www.sensorsportal.com/HTML/E-SHOP/PRODUCTS_4/UFDC_1.htm)

Promoted by IFSA

## Status of the MEMS Industry Report up to 2017

Report includes MEMS device markets, key players strategies, key industry changes and MEMS financial analysis. It also includes major MEMS manufacturing evolutions as well as an update on the "emerging" MEMS device markets.

Order online:

[http://www.sensorsportal.com/HTML/Status\\_of\\_MEMS\\_Industry.htm](http://www.sensorsportal.com/HTML/Status_of_MEMS_Industry.htm)



The Fourth International Conference on Sensor Device Technologies and Applications

## SENSORDEVICES 2013

25 - 31 August 2013 - Barcelona, Spain

**Tracks:** Sensor devices - Ultrasonic and Piezosensors - Photonics - Infrared - Gas Sensors - Geosensors - Sensor device technologies - Sensors signal conditioning and interfacing circuits - Medical devices and sensors applications - Sensors domain-oriented devices, technologies, and applications - Sensor-based localization and tracking technologies - Sensors and Transducers for Non-Destructive Testing

**Deadline for papers: 30 March 2013**

<http://www.iaia.org/conferences2013/SENSORDEVICES13.html>



The Seventh International Conference on Sensor Technologies and Applications

**Deadline for papers:  
30 March 2013**

## SENSORCOMM 2013

25 - 31 August 2013 - Barcelona, Spain

**Tracks:** Architectures, protocols and algorithms of sensor networks - Energy, management and control of sensor networks - Resource allocation, services, QoS and fault tolerance in sensor networks - Performance, simulation and modelling of sensor networks - Security and monitoring of sensor networks - Sensor circuits and sensor devices - Radio issues in wireless sensor networks - Software, applications and programming of sensor networks - Data allocation and information in sensor networks - Deployments and implementations of sensor networks - Under water sensors and systems - Energy optimization in wireless sensor networks

<http://www.iaia.org/conferences2013/SENSORCOMM13.html>



The Sixth International Conference on Advances in Circuits, Electronics and Micro-electronics

## CENICS 2013

25 - 31 August 2013 - Barcelona, Spain

**Deadline for papers: 30 March 2013**

**Tracks:** Semiconductors and applications - Design, models and languages - Signal processing circuits - Arithmetic computational circuits - Microelectronics - Electronics technologies - Special circuits - Consumer electronics - Application-oriented electronics

<http://www.iaia.org/conferences2013/CENICS13.html>

## Aims and Scope

*Sensors & Transducers* is a peer reviewed international, interdisciplinary journal that provides an advanced forum for the science and technology of physical, chemical sensors and biosensors. It publishes original research articles, timely state-of-the-art reviews and application specific articles with the following devices areas:

- Physical, chemical and biosensors;
- Digital, frequency, period, duty-cycle, time interval, PWM, pulse number output sensors and transducers;
- Theory, principles, effects, design, standardization and modeling;
- Smart sensors and systems;
- Sensor instrumentation;
- Virtual instruments;
- Sensors interfaces, buses and networks;
- Signal processing and interfacing;
- Frequency (period, duty-cycle)-to-code converters, ADC;
- Technologies and materials;
- Nanosensors;
- Microsystems;
- Applications.

Further information on this journal is available from the Publisher's web site:  
<http://www.sensorsportal.com/HTML/DIGEST/Submission.htm>

## Subscriptions

An annual subscription includes 12 regular issues and some special issues. Annual subscription rates for 2013 are the following:

Electronic version (in printable pdf format): 400.00 EUR

Printed with b/w illustrations: 640.00 EUR

Printed full color version: 760.00 EUR

40 % discount is available for IFSA Members.

Prices include shipping costs by mail. Further information about subscription is available through IFSA Publishing's web site: [http://www.sensorsportal.com/HTML/DIGEST/Journal\\_Subscription.htm](http://www.sensorsportal.com/HTML/DIGEST/Journal_Subscription.htm)

## Advertising Information

If you are interested in advertising or other commercial opportunities please e-mail [sales@sensorsportal.com](mailto:sales@sensorsportal.com) and your enquiry will be passed to the correct person who will respond to you within 24 hours. Please download also our Media Planner 2013: [http://www.sensorsportal.com/DOWNLOADS/Media\\_Planner\\_2013.pdf](http://www.sensorsportal.com/DOWNLOADS/Media_Planner_2013.pdf)

## Books for Review

Publications should be sent to the IFSA Publishing Office: Ronda de Ramon Otero Pedrayo, 42C, 1-5, 08860, Castelldefels, Barcelona, Spain.

## Abstracting Services

This journal is cited, indexed and abstracted by Chemical Abstracts, EBSCO Publishing, IndexCopernicus Journals Master List, ProQuest Science Journals, CAS Source Index (CASSI), Ulrich's Periodicals Directory, Scirus, Google Scholar, etc. Since 2011 *Sensors & Transducers* journal is covered and indexed by EI Compendex index (including a Scopus, Embase, Engineering Village and Reaxys) in *Elsevier* products.

## Instructions for Authors

Please visit the journal web page <http://www.sensorsportal.com/HTML/DIGEST/Submission.htm> Authors must follow the instructions very carefully when submitting their manuscripts. Manuscript must be send electronically in both: MS Word 2003 for Windows (doc) and Acrobat (pdf) formats by e-mail: [editor@sensorsportal.com](mailto:editor@sensorsportal.com)

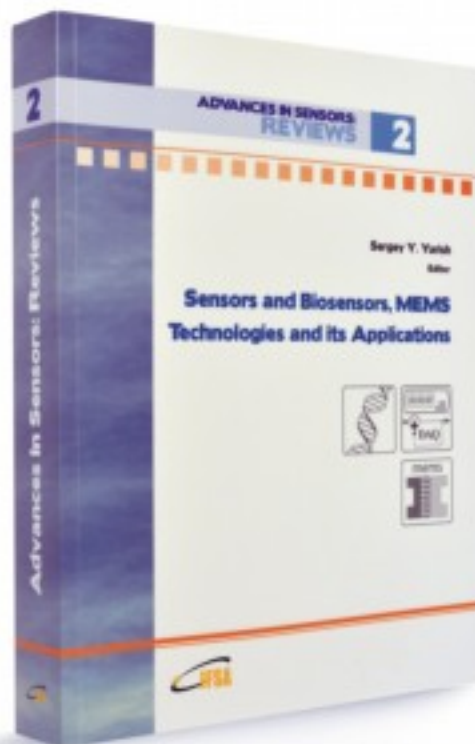
## ADVANCES IN SENSORS: REVIEWS

# 2

**Sergey Y. Yurish**

**Editor**

# Sensors and Biosensors, MEMS Technologies and its Applications



The second volume titled '*Sensors and Biosensors, MEMS Technologies and its Applications*' from the '*Advances in Sensors: Review*' Book Series contains eighteen chapters with sensor related state-of-the-art reviews and descriptions of the latest achievements written by experts from academia and industry from 12 countries: China, India, Iran, Malaysia, Poland, Singapore, Spain, Taiwan, Thailand, UK, Ukraine and USA.

This book ensures that our readers will stay at the cutting edge of the field and get the right and effective start point and road map for the further researches and developments. By this way, they will be able to save more time for productive research activity and eliminate routine work.

Built upon the series *Advances in Sensors: Reviews* - a premier sensor review source, it presents an overview of highlights in the field and becomes. This volume is divided into three main parts: physical sensors, biosensors, nanoparticles, MEMS technologies and applications. With this unique combination of information in each volume, the *Advances in Sensors: Reviews* Book Series will be of value for scientists and engineers in industry and at universities, to sensors developers, distributors, and users.

Like the first volume of this Book Series, the second volume also has been organized by topics of high interest. In order to offer a fast and easy reading of the state of the art of each topic, every chapter in this book is independent and self-contained. The eighteen chapters have the similar structure: first an introduction to specific topic under study; second particular field description including sensing applications.

Order online:

[http://sensorsportal.com/HTML/BOOKSTORE/Advance\\_in\\_Sensors\\_Vol\\_2.htm](http://sensorsportal.com/HTML/BOOKSTORE/Advance_in_Sensors_Vol_2.htm)



[www.sensorsportal.com](http://www.sensorsportal.com)

ISSN 1726- 5479



9 771726 547001